

PATENT APPLICATION

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Hiroyuki KUMAKURA

Application No.: New U.S. Patent Application

Filed: January 18, 2001

Docket No.: 108379

For: ADHESIVE COMPOSITION

PRELIMINARY AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D. C. 20231

Sir:

Prior to initial examination, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend claims 3 and 4 as follows:

Claim 3, line 2, change "Claim 1 or Claim 2," to -- Claim 1, --.

Claim 4, line 4, change "any of Claims 1 to 3." to -- Claim 1. --.

Please add claims 5-7 as follows:

5. The anisotropic conductive adhesive composition according to Claim 2, further comprising electrically conductive particles. --

-- 6. A connected structure, wherein electrodes on a plastic substrate and on a circuit board that are facing each other are connected by the adhesive composition according to Claim 2. --